

REMARKS

The specification has been amended to clarify confusing terms. The term "a work-attaching region (3a)" has been changed to "a work-attaching portion (3a)" because the portion (3a) does not denote simply an area but constitutes a portion (section) of the die-bonding adhesive layer (3) itself as shown in Figs 1 and 2, for example. Further, the term "a region (2a)", for example, has been changed to "a portion (2a)" for the same reason. Also, the term "a layer (2a)" has been changed to "a portion (2a)" because the "layer (2a)" implies a separate layer although the portion (2a) constitutes a portion (section) of the pressure-sensitive adhesive layer (2) as shown in Figs. 1 and 2, for example.

In light of the interview, Claim 1 has been amended merely to clarify that the interface (A) and the interface (B) are both formed between the die-bonding adhesive layer and the pressure-sensitive adhesive layer at specific positions. Claims 2-5 and 8 have been amended consistently with the amendments to Claim 1. Claims 6, 7, and 9-14 have been canceled without prejudice.

No new matter has been added, or no new issue is raised because the amendments are requested merely in order to clarify the invention. Applicant respectfully requests entry of the amendments and reconsideration of the application in view of the amendments and the following remarks.

Rejection Under 35 U.S.C. § 112

Claims 1-5 and 8 have been rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

The claims have been amended to clarify the invention. Referring to an embodiment of Fig. 1, a dicing/die-bonding film comprising:

- a supporting base material (1),
- a pressure-sensitive adhesive layer (2) formed on the supporting base material,
- a die-bonding adhesive layer (3) formed on the pressure-sensitive adhesive layer (2),
- said die-bonding adhesive layer (3) being comprised of a work-attaching portion (3a) on which a work (W) is to be attached and a no-work-attaching portion (3b) other than the work-attaching portion (3a),

an interface (A) formed between the work-attaching portion (3a) of the die-bonding adhesive layer (3) and a portion (2a) of the pressure-sensitive adhesive layer (2) in contact with the work-attaching portion (3a), and

an interface (B) formed between a part or a whole of the no-work-attaching portion (3b) of the die-bonding adhesive layer (3) and a portion (2b) of the pressure-sensitive adhesive layer (2) in contact with the part or the whole of the no-work-attaching portion (3b),

wherein releasability between the pressure-sensitive adhesive layer (2) and the die-bonding adhesive layer (3) at the interface (A) is higher than the releasability at the interface (B).

Claims 2-5 and 8 have also been amended consistently with the amendments to Claim 1.

Applicant believes that the claims as amended herein clearly define the invention. Applicant respectfully requests withdrawal of this rejection.

Rejection Under 35 U.S.C. § 102

Claims 1-5 and 8 have been rejected under 35 U.S.C. § 102(b) as being anticipated by Senoo ('061). The Examiner asserts that Senoo teaches the dicing/die bonding film of Claim 1 by referring to Col. 5, lines 40-67 and Col. 6, lines 5-30. Applicant respectfully traverses this rejection.

In Claim 1, the interface (A) and the interface (B) are both formed between (i) the die-bonding adhesive layer on which a work is to be placed and (ii) the pressure-sensitive adhesive layer formed underneath the die-bonding adhesive layer. In Senoo, the work 6 is placed on the pressure-sensitive adhesive layer 5a which is unpeelably laminated to the base 5b (col. 6, lines 60-62). Clearly, in Senoo, there is no die-bonding adhesive layer separately from the pressure-sensitive adhesive layer 5a. The interface between the pressure-sensitive adhesive layer 13 and the ring frame 1 in Senoo (col. 6, lines 5-7) is irrelevant to the interface (A) or (B) of Claim 1. Further, the interface between the base film 12 and the pressure-sensitive adhesive layer 5a of the dicing sheet 5 in Senoo (col. 6, lines 7-9) is also irrelevant to the interface (A) or (B).

In view of the foregoing, Senoo in no way could anticipate Claim 1. The remaining claims depend from Claim 1, and at least for the reason, Senoo also could not anticipate the remaining claims. Applicant respectfully requests withdrawal of the rejection.

CONCLUSION

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In light of the Applicant's amendments to the claims and the foregoing Remarks, it is respectfully submitted that the present application is in condition for allowance. Should the Examiner have any remaining concerns which might prevent the prompt allowance of the application, the Examiner is respectfully invited to contact the undersigned at the telephone number appearing below.

Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Respectfully submitted,

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